



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-01-04
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EYWQ*Q994AR6	A	SA1A	2016-01-04
Amount	UoM	Unit type	ST ECOPACK Grade	
21.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3x3x1	10	No lead	
Comment	Package: WQ VDFPN 3x3x1.0 10 PITCH 0.50; MDF valid for TS4994IQT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EYWQ*Q994AR6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.709	mg	supplier	die	Silicon (Si)	7440-21-3		1.681	mg	983616	80048
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	3511	286
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1170	95
Die				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.004	mg	2341	190
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.016	mg	9362	762
Lead-frame	Copper & its alloys	8.597		Supplier	Alloy	Copper (Cu)	7440-50-8		8.475	mg	985809	403571
Lead-frame				Supplier	Alloy	Phosphorus (P)	12185-10-3		0.022	mg	2559	1048
Lead-frame				Supplier	Alloy	Zinc (Zn)	7440-66-6		0.008	mg	931	381
Lead-frame				Supplier	Alloy	Silver(Ag)	7440-22-4		0.092	mg	10701	4381
Die attach	Other Organic Materials	0.213	mg	supplier	glue	Silver(Ag)	7440-22-4		0.17	mg	798122	8095
Die attach				supplier	glue or tape	Epoxy resin	9003-36-5		0.039	mg	183099	1857
Die attach				supplier	glue or tape	t-Butyl phenyl glycidyl	3101-60-8		0.004	mg	18779	190
Bonding wire	Precious metals	0.083	mg	supplier	wire	Gold (Au)	7440-57-5		0.083	mg	1000000	3952
Encapsulation	Other Organic Materials	10.297	mg	Supplier	Molding compound	Silica, vitreous	60676-86-0		9.757	mg	947558	464619
Encapsulation				Supplier	Molding compound	Phenol Resin	Proprietary		0.391	mg	37972	18619
Encapsulation				Supplier	Molding compound	Carbon black	1333-86-4		0.033	mg	3205	1571
Encapsulation				Supplier	Molding compound	Brominated epoxy resin	40039-93-8		0.058	mg	5633	2762
Encapsulation				Supplier	Molding compound	AntimonyTrioxide	1309-64-3		0.058	mg	5633	2762
Finishing	Solder	0.1	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.1	mg	1000000	4762